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Laser Applications in Microelectronic and Optoelectronic Manufacturing (LAMOM) XXV

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Contents

v	<i>Authors</i>
vii	<i>Conference Committee</i>

LASER PROCESSING OF POLYMERS

- 11267 06 **Optical waveguide on silicon made by zone melting method** [11267-42]
- 11267 09 **High speed laser printing and sintering of flexible RFID antennas and fingerprint sensors** [11267-47]

ULTRAFAST LASER-INDUCED MODIFICATIONS IN TRANSPARENT MATERIALS: JOINT SESSION WITH 11267 AND 11270

- 11267 0B **Laser induced modifications in transparent materials using azimuthally modulated axicon beams** [11267-9]

LASER-BASED PROCESSES FOR ELECTRONICS

- 11267 0F **Surface functionalization of flexographic printing forms using a femtosecond laser for adjustable material transfer in MID production processes** [11267-13]
- 11267 0H **Laser processing of titanium: oxide formation for electronic applications** [11267-15]

LASER NANOPROCESSING

- 11267 0I **Nanoparticle synthesis via femtosecond laser reduction in liquid (Invited Paper)** [11267-16]
- 11267 0J **Energy generation on an array of nanoparticles on a surface** [11267-17]
- 11267 0L **Effect of front-contact laser texturing in thin-film solar cells** [11267-19]

UPSCALING LASER PROCESSING UTILIZING ADVANCED BEAM SHAPING

- 11267 0P **High-precision ultrashort pulsed laser processing of metal foils using an advanced multibeam optic (Best Student Paper Award)** [11267-23]

11267 OR **Scaling percussion drilling processes by ultrashort laser pulses using advanced beam shaping**
[11267-25]

TOWARDS HIGH-EFFICIENT LASER ABLATION

11267 OT **Machining metals and silicon with GHz bursts: surprising tremendous reduction of the specific removal rate for surface texturing applications** [11267-27]

11267 OV **Micromachining flexibility by tunable ultrashort pulse duration, pulse-on-demand, and hybrid processing from single pulse to GHz burst with TruMicro Series 2000** [11267-29]

ULTRAFast LASER PROCESSING OF GLASS, CERAMICS AND SEMICONDUCTORS

11267 OW **Ultrafast and precision processing of glass by selective absorption of fiber-laser pulse into femtosecond-laser-induced filament (Invited Paper)** [11267-30]

11267 OZ **Micro laser assisted single point diamond turning of brittle and hard materials** [11267-33]

MODELLING AND PROCESS CONTROL

11267 10 **High-precision laser ablation using OCT closed-loop control (Invited Paper)** [11267-35]

11267 13 **Position observer based galvanometer scanner and XY stage synchronization for large area processing** [11267-38]

INTEGRATION OF DEVICES INSIDE BULK TRANSPARENT MATERIALS

11267 14 **3D glass nanofluidics fabricated by femtosecond laser processing for study of cancer cell metastasis and invasion (Invited Paper)** [11267-39]

11267 17 **From proof of principle to 98.5% yield of a high-speed laser processing tool (Invited Paper)**
[11267-44]

POSTER SESSION

11267 1B **Fabrication of sub-micrometer periodic nanostructures using pulsed laser interference for efficient light trapping in optoelectronic devices** [11267-46]

Authors

Numbers in the index correspond to the last two digits of the seven-digit citation identifier (CID) article numbering system used in Proceedings of SPIE. The first five digits reflect the volume number. Base 36 numbering is employed for the last two digits and indicates the order of articles within the volume. Numbers start with 00, 01, 02, 03, 04, 05, 06, 07, 08, 09, 0A, 0B...0Z, followed by 10-1Z, 20-2Z, etc.

Ankri, Jonathan, 09
Arnaldo, Daniel, 09
Arutinov, Gari, 09
Auyeung, Raymond C. Y., 0H
Baitrukonis, Justas, 0B
Barthels, T., 0P
Behera, S., 1B
Bhut, Bhavesh A., 13
Bodlapati, Charan, 0Z
Boley, Steffen, 10
Braz, Nuno, 09
Budnicki, Aleksander, 0V
Buser, Matthias, 10
Butkus, Simas, 0T
Canteli, David, 0L
Chaja, Michalina V., 0T
Charipar, Kristin M., 0H
Charipar, Nicholas A., 0H
Chou, M. F., 0J
Cobb, Brian, 09
De la Vega, Fernando, 09
Diekamp, Holger, 0V
Dowling, Keith J., 13
Eberhardt, Christian, 0V
Fehrenbacher, Axel, 0V
Fernández, Susana, 0L
Flamm, D., 0R
Fu, T. C., 0J
Fuehrra, Benjamin, 0V
Gafner, Markus, 0T
Geremia, Riccardo, 09
Giesbers, Merijn, 09
Ginter, Markus, 0V
Gotovski, Pavel, 0B
Graf, Thomas, 10
Grossmann, D., 0R
Han, I. S., 1B
Hanuka, Uriel, 06
Hellstern, J., 0R
Hirsiger, Thomas, 0T
Hoffmann, Gerd-Albert, 0F
Holder, Daniel, 10
Hong, J. Y., 0J
Hopkinson, M., 1B
Hsu, Yu John, 13
Ito, Yusuke, 0W
Jansen, Florian, 0V
Jäschke, Peter, 0F
Jin, C., 1B
Jukna, Vytautas, 0B
Kabla, Ayala, 09
Kailerle, Stefan, 0F
Kalaitzis, Agamemnon, 09
Kanal, Florian, 0V
Kang, Di, 0Z
Kariyapperuma, Darshana, 09
Karnakis, Dimitris, 09
Kawano, H., 14
Kim, Heungsoo, 0H
Koch, Jürgen, 0F
Koritsoglou, Olga, 09
Kumkar, M., 0R
Leis, Artur, 10
Li, Jin, 13
Lucas, Mark S., 13
Makrygianni, Marina, 09
Melamed, Alon, 09
Melamed, Semyon, 09
Miyawaki, A., 14
Molpeceres, Carlos, 0L
Morales, Miguel, 0L
Musi, Christopher, 0H
Nacius, Ernestas, 0B
Nagasawa, Ikuo, 0W
Nagato, Keisuke, 0W
Navare, Jayesh, 0Z
Neuenschwander, Beat, 0T
Nießen, M., 0P
Norval, Shane, 09
Obata, K., 14
Orlov, Sergej, 0B
Overmeyer, Ludger, 0F
Piqué, Alberto, 0H
Price, Richard, 09
Quentin, Ulf, 0V
Ravindra, Deepak, 0Z
Reininghaus, M., 0P
Remund, Stefan, 0T
Sailer, Marc, 0R, 0V
Santos, José D., 0L
Scelle, Raphael, 0V
Schwarzbaum, Arye, 09
Serien, D., 14
Shahar, Amit, 13
Shahinian, Hossein, 0Z
Shibata, Akihiro, 0W
Sima, F., 14
Sinvani, Moshe, 06

Sivam, Seethram, 13
Slevas, Paulius, 0B
Sperling, Patrick, 0V
Sugioka, K., 14
Sugita, Naohiko, 0W
Sutter, Dirk H., 0V
Tan, Chuong, 0V
Terbrueggen, Ralf, 17
Theodorakos, Ioannis, 09
Tibbetts, Katharine Moore, 0I
Tiferet, Maor, 06
Too, Patrick, 09
Torres, Ignacio, 0L
Tuohi, Simon, 09
Ulcinas, Orestas, 0B
Urniezius, Aivaras, 0T
Wang, Y., 0P
Wang, Y., 1B
Weber, Rudolf, 10
Wei, P. S., 0J
Wienke, Alexander, 0F
Yoshizaki, Reina, 0W
Zacharatos, Filimon, 09
Zalevsky, Zeev, 06
Zaytsev, Dmytro, 0Z
Zergioti, Ioanna, 09
Zigman, Yair, 06

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- 1 LAMOM XXV Anniversary
Gediminas Račiukaitis, Center for Physical Sciences and Technology (Lithuania)
- 2 Laser Processing of Polymers
Jie Qiao, Rochester Institute of Technology (United States)
- 3 Ultrafast Laser-induced Modifications in Transparent Materials: Joint Session with 11267 and 11270
Roberto Osellame, CNR-Istituto di Fotonica e Nanotecnologie (Italy)
- 4 Laser-based Processes for Electronics
Carlos Molpeceres, Universidad Politécnica de Madrid (Spain)
Jie Qiao, Rochester Institute of Technology (United States)
- 5 Laser Nanoprocessing
Tadatake Sato, National Institute of Advanced Industrial Science and Technology (Japan)
- 6 Upscaling Laser Processing Utilizing Advanced Beam Shaping
Guido Hennig, Daetwyler Graphics AG (Switzerland)
- 7 Towards High-efficient Laser Ablation
Carlos Molpeceres, Universidad Politécnica de Madrid (Spain)
- 8 Ultrafast Laser Processing of Glass, Ceramics and Semiconductors
Aiko Narazaki, National Institute of Advanced Industrial Science and Technology (Japan)
- 9 Modelling and Process Control
Gediminas Račiukaitis, Center for Physical Sciences and Technology (Lithuania)

- 10 Integration OD Devices Inside Bulk Transparent Materials
Carlos Molpeceres, Universidad Politécnica de Madrid (Spain)

